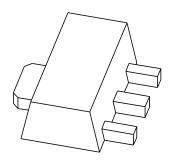
## **DISCRETE SEMICONDUCTORS**

## DATA SHEET



# BC868 NPN medium power transistor

Product specification Supersedes data of September 1994 File under Discrete Semiconductors, SC04 1997 Mar 19





## NPN medium power transistor

**BC868** 

#### **FEATURES**

- High current (max. 1 A)
- Low voltage (max. 20 V).

#### **APPLICATIONS**

- General purpose switching and amplification
- Power applications such as audio output stages.

#### **DESCRIPTION**

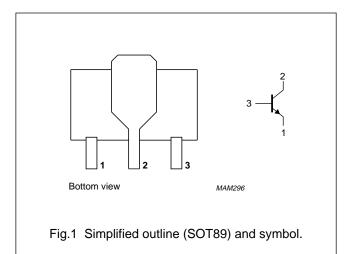
NPN medium power transistor in a SOT89 plastic package. PNP complement: BC869.

#### **MARKING**

TYPE NUMBER	MARKING CODE
BC868	CAC
BC868-10	CBC
BC868-16	CCC
BC868-25	CDC

#### **PINNING**

PIN	DESCRIPTION
1	emitter
2	collector
3	base



#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	32	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	20	V
I <sub>CM</sub>	peak collector current		_	2	Α
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	_	1.4	W
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 500 mA; V <sub>CE</sub> = 1 V	85	375	
f <sub>T</sub>	transition frequency	$I_C = 10 \text{ mA}; V_{CE} = 5 \text{ V}; f = 100 \text{ MHz}$	40	_	MHz

## NPN medium power transistor

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#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	PARAMETER CONDITIONS		MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	32	V
$V_{CEO}$	collector-emitter voltage	open base	_	20	V
$V_{EBO}$	emitter-base voltage	open collector	_	5	V
I <sub>C</sub>	collector current (DC)		_	1	Α
I <sub>CM</sub>	peak collector current		_	2	А
I <sub>BM</sub>	peak base current		_	200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	1.4	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		<b>–65</b>	+150	°C

#### Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>. For other mounting conditions, see "Thermal considerations for SOT89 in the General part of handbook SC04".

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	89	K/W
R <sub>th j-s</sub>	thermal resistance from junction to soldering point		8	K/W

#### Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>. For other mounting conditions, see "Thermal considerations for SOT89 in the General part of handbook SC04".

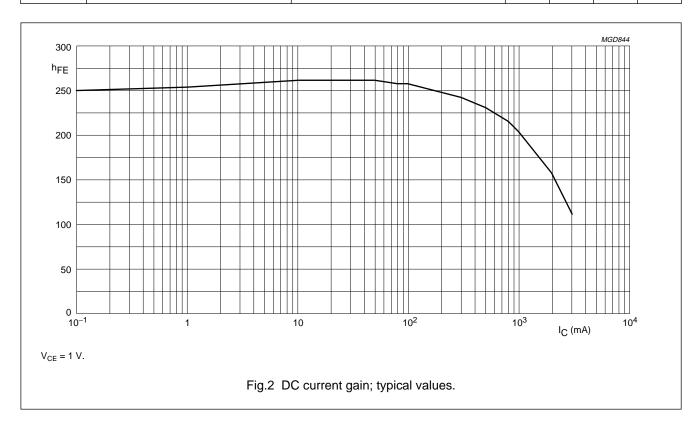
## NPN medium power transistor

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#### **CHARACTERISTICS**

 $T_j = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 25 V	_	_	100	nA
		I <sub>E</sub> = 0; V <sub>CB</sub> = 25 V; T <sub>j</sub> = 150 °C	_	_	10	μΑ
I <sub>EBO</sub>	emitter cut-off current	I <sub>C</sub> = 0; V <sub>EB</sub> = 5 V	_	_	100	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 10 V	50	_	_	
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 1 V; see Fig.2				
		I <sub>C</sub> = 500 mA	85	_	375	
		I <sub>C</sub> = 1 A	60	_	_	
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 500 mA; V <sub>CE</sub> = 1 V; see Fig.2				
	BC868-10		-	_	160	
	BC868-16		100	_	250	
	BC868-25		160	_	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA	_	_	500	mV
V <sub>BE</sub>	base-emitter voltage	I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 10 V	_	620	_	mV
		I <sub>C</sub> = 1 A; V <sub>CE</sub> = 1 V	_	_	1	V
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 10 mA; V <sub>CE</sub> = 5 V; f = 100 MHz	40	_	_	MHz
h <sub>FE1</sub> h <sub>FE2</sub>	DC current gain ratio of the complementary pairs	I <sub>C</sub>   = 0.5 A;   V <sub>CE</sub>   = 1 V	_	_	1.6	



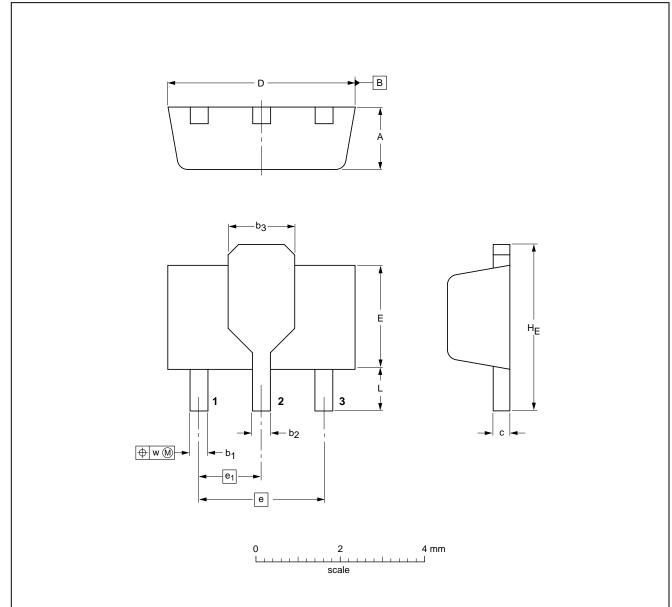
## NPN medium power transistor

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#### **PACKAGE OUTLINE**

Plastic surface mounted package; collector pad for good heat transfer; 3 leads

**SOT89** 



DIMENSIONS	(mm are	the original	dimensions)

U	INIT	A	b <sub>1</sub>	b <sub>2</sub>	b <sub>3</sub>	С	D	E	е	e <sub>1</sub>	HE	L min.	w
r	mm	1.6 1.4	0.48 0.35	0.53 0.40	1.8 1.4	0.44 0.37	4.6 4.4	2.6 2.4	3.0	1.5	4.25 3.75	0.8	0.13

OUTLINE		REFERENCES			EUROPEAN ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT89					$ \  \    \bigoplus  $	97-02-28	

#### NPN medium power transistor

**BC868** 

#### **DEFINITIONS**

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

## NPN medium power transistor

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